

PCN#20210927002.1 Qualification of new Fab site (RFAB) using qualified Process Technology, Die Revision, and additional BOM option for select devices

Change Notification / Sample Request

Date:September 28, 2021To:TOKYO ELECTRON DEVICE (DSTR) PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments (TI). The details of this change are on the following pages, and are in alignment with our standard product change notification (PCN) <u>process</u>.

TI requires acknowledgement of receipt of this notification within 30 days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If samples or additional data are required, requests must be received within 30 days of this notification, given that samples are not built ahead of the change.

The Proposed First Ship date in this PCN letter is the earliest possible date that customers could receive the changed material. It is our commitment that the changed device will not ship before that date. If samples are requested within the 30 day sample request window, customers will still have 30-days to complete their evaluation regardless of the proposed 1st ship date.

This particular PCN is related to TI's previous announcement to close our two remaining factories with 150-millimeter production (DFAB in Dallas, Texas, and SFAB in Sherman, Texas). As referenced in the "reason for change" below, these changes are part of our multiyear plan to transition these products to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the PCN Team (<u>PCN ww admin team@list.ti.com</u>). For sample requests or sample related questions, contact your local Field Sales Representative. As always, we thank you for your continued business.

PCN Team SC Business Services

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
CD74HC238E	null
SN74HC166N	null
SN74HC139N	null
SN74HC151N	null
SN74HC273N	null
SN74HC540PWR	null
SN74HC240PWR	null
SN74HC541NSR	null
SN74HC540N	null
SN74HC240N	null
SN74HC240NSR	null
SN74HC541N	null
SN74HC273NSR	null
SN74HC574PWR	null
SN74HC273PWR	null
SN74HC241PWR	null
CD74HC138E	null
CD74HC259E	null
SN74HC367N	null
SN74HC541PWR	null
SN74HC541ANSR	null
SN74HC540NSR	null
SN74HC595N	null
SN74HC157N	null
SN74HC573NSR	null
SN74HC373N	null
SN74HC374NSR	null
SN74HC373NSR	null
SN74HC138N	null
SN74HC574NSR	null
SN74HC377NSR	null
SN74HC174N	null
SN74HC273DBR	null
SN74HC165N	null

Technical details of this Product Change follow on the next page(s).

PCN Numbe		02109270					Date:	September 28, 202						
Title:Qualification of new Fab site (RFAB) using qualified Process Technology, Die Revision, and additional BOM option for select devices														
Customer C	ontact:	<u>P</u>	CN Mana	<u>ger</u>		Dept	:	Quality Services						
Proposed 1 ^s	st Ship Da	ate: D	Dec 26, 20	021	Estima Availa			Date provided at sample request.						
Change Typ	e:							· · ·						
Assembl	y Site		Asser	nbly Pro	ocess	\geq	Asse	mbly Materials						
Design Electrical Specification Mechanical Specification														
Test Site	ē		Packi	ng/Ship	ping/Labeling		Test	Process						
Wafer Bu	ump Site		Wafe	r Bump	Material		Wafe	r Bump Process						
🛛 Wafer Fa	ab Site		Wafe	r Fab M	aterials		Wafe	r Fab Process						
			Part r	number	change									
				PCN I	Details									
Description	of Chanc	ie:												
			announce	e the qu	alification of a	a new	fab & pr	ocess technology						
								luct affected section.						
Construction														
	Curren	t Fab Site	e		Current Fab Site Additional Fab Site									
Current Fab Process Wafer Additional Process Wafer Site Diameter Fab Site Diameter														
	ab Pr	ocess	-	-			Process							
SFAB	_	CMOS	-	eter	Additional Fab Site RFAB			Diameter						
Site SFAB	H	CMOS	Diame 150 r	eter mm	Fab Site RFAB		Process LBC9							
Site	H	CMOS	Diame 150 r	eter mm	Fab Site RFAB			Diameter						
Site SFAB The die was a	H Halso chang	CMOS ged as a re	Diame 150 r esult of th	eter nm ne proce	Fab Site RFAB		LBC9	Diameter						
Site SFAB The die was a	H Halso chang	CMOS ged as a re	Diame 150 r esult of th	eter nm ne proce	Fab Site RFAB ess change.	evices	LBC9	Diameter						
Site SFAB The die was a	H Halso chang	CMOS ged as a re be a BOM	Diame 150 r esult of th option in	eter mm ne proce	Fab Site RFAB ess change. ed for these de Current	evices	LBC9	Diameter						
Site SFAB The die was a	H Halso chang	CMOS ged as a re be a BOM Bond	Diame 150 r esult of th option in wire	eter mm ne proce	Fab Site RFAB ess change. ed for these de	evices	LBC9	Diameter						
Site SFAB The die was a Additionally,	H also chang there will	CMOS ged as a re be a BOM	Diame 150 r esult of th option in wire	eter mm ne proce	Fab Site RFAB ess change. ed for these de Current	evices	LBC9 : itional	Diameter						
Site SFAB The die was a Additionally, Reason for (H also chang there will Change:	CMOS ged as a re be a BOM Bond diamete	Diame 150 r esult of th option in wire er (Cu)	eter mm ne proce ntroduce	Fab Site RFAB ess change. ed for these de Current .96 mils	evices Add 0.8	LBC9 : itional 3 mils	Diameter 300 mm						
Site SFAB The die was a Additionally, Reason for (These change	H also chang there will Change: es are par	CMOS ged as a re be a BOM Bond diamete	Diame 150 r esult of th option in wire er (Cu) ultiyear p	eter mm he proce htroduce 0 0 0 0 0 0 0 0 0 0 0 0 0	Fab Site RFAB ess change. ed for these de Current .96 mils	evices Add 0.8	LBC9 : itional 3 mils	Diameter 300 mm 150-milimeter						
Site SFAB The die was a Additionally, Reason for (These change factories to n	H also chang there will Change: es are par ewer, mo	CMOS ged as a re be a BOM Bond diamete t of our m re efficien	Diame 150 r esult of th option in wire er (Cu) ultiyear p t manufae	eter mm he proce htroduce 0 0 0 0 0 0 0 0 0 0 0 0 0	Fab Site RFAB ess change. ed for these de Current .96 mils rransition proc processes and	evices Add 0.8	LBC9 : itional 3 mils	Diameter 300 mm						
Site SFAB The die was a Additionally, Additionally, Meason for (These change factories to n commitment	H also chang there will Change: es are par ewer, mo to produc	CMOS ged as a re be a BOM Bond diamete t of our m re efficien ct longevity	Diame 150 r esult of th option in wire er (Cu) ultiyear p t manufac y and sup	eter mm he proce htroduce 0 0 0 0 0 0 0 0 0 0 0 0 0	Fab Site RFAB ess change. ed for these de Current .96 mils cransition proc processes and tinuity.	evices Add 0.8 ducts f	LBC9 : itional 3 mils from our hologies,	Diameter 300 mm 150-milimeter underscoring our						
Site SFAB The die was a Additionally, Additionally, Meason for (These change factories to n commitment Anticipated	H also chang there will Change: es are par ewer, mo to produc	CMOS ged as a re be a BOM Bond diamete t of our m re efficien ct longevity	Diame 150 r esult of th option in wire er (Cu) ultiyear p t manufac y and sup	eter mm he proce htroduce 0 0 0 0 0 0 0 0 0 0 0 0 0	Fab Site RFAB ess change. ed for these de Current .96 mils cransition proc processes and tinuity.	evices Add 0.8 ducts f	LBC9 : itional 3 mils from our hologies,	Diameter 300 mm 150-milimeter						
Site SFAB The die was a Additionally, Additionally, Meason for (These change factories to n commitment	H also chang there will Change: es are par ewer, mo to produc	CMOS ged as a re be a BOM Bond diamete t of our m re efficien ct longevity	Diame 150 r esult of th option in wire er (Cu) ultiyear p t manufac y and sup	eter mm he proce htroduce 0 0 0 0 0 0 0 0 0 0 0 0 0	Fab Site RFAB ess change. ed for these de Current .96 mils cransition proc processes and tinuity.	evices Add 0.8 ducts f	LBC9 : itional 3 mils from our hologies,	Diameter 300 mm 150-milimeter underscoring our						
Site SFAB The die was a Additionally, Additionally, Meason for (These change factories to n commitment Anticipated	H also chang there will Change: es are par ewer, mo to produc impact o	CMOS ged as a re be a BOM Bond diamete t of our m re efficient t longevity on Form, I	Diame 150 r esult of th option in wire er (Cu) ultiyear p t manufac y and sup Fit, Func	eter mm he proce htroduce 0 0 0 0 0 0 0 0 0 0 0 0 0	Fab Site RFAB ess change. ed for these de Current .96 mils cransition proc processes and tinuity.	evices Add 0.8 ducts f	LBC9 : itional 3 mils from our hologies,	Diameter 300 mm 150-milimeter underscoring our						

change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
🛛 No Change	🛛 No Change	🛛 No Change	🛛 No Change

Changes to product identification resulting from this PCN:

Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
SH-BIP-1	SHE	USA	Sherman
RFAB	RFB	USA	Richardson

Die Rev:

Current	New
Die Rev [2P]	Die Rev [2P]
A, E, F, G, H, J, -	Α

Sample product shipping label (not actual product label)

TEXAS INSTRUMENTS MADE IN: Malaysia 2DC: 20:	€ 64		(1P) SN74LS07NSR (Q) 2000 (D) 0336
MSL 2 /260C/1 YEAR MSL 1 /235C/UNLIM			(31T)LOT: 3959047MLA (4W) TKY(1T) 7523483SI2 (P)
LBL: 5A (L)TO	: 1750	Receiption Cons	(2P) REV: (V) 0033317 (20L) CSO. SHE (21L) CCO.USA (22L) ASO: MLA (23L) ACO: MYS

Product Affected:

CD74HC138E	SN74HC151N		SN74HC541ANSR
		SN74HC273NSR	
CD74HC138EE4	SN74HC157N	SN74HC273PWR	SN74HC541DBR
CD74HC237E	SN74HC157NE4	SN74HC273PWRG4	SN74HC541N
CD74HC237EE4	SN74HC165N	SN74HC367N	SN74HC541NE4
CD74HC238E	SN74HC165NE4	SN74HC373N	SN74HC541NSR
CD74HC238EE4	SN74HC166N	SN74HC373NE4	SN74HC541PWR
CD74HC259E	SN74HC174N	SN74HC373NSR	SN74HC573AN
CD74HC273E	SN74HC174NE4	SN74HC373NSRE4	SN74HC573ANE4
CD74HC373E	SN74HC240N	SN74HC373PWR	SN74HC573APWR
CD74HC373EE4	SN74HC240NE4	SN74HC373PWRE4	SN74HC573APWRG4
CD74HC374E	SN74HC240NSR	SN74HC374N	SN74HC573NSR
CD74HC377PWR	SN74HC240NSRE4	SN74HC374NE4	SN74HC574DBR
CD74HC377PWRG4	SN74HC240PWR	SN74HC374NSR	SN74HC574DBRG4
CD74HC541E	SN74HC240PWRG4	SN74HC374PWR	SN74HC574N
CD74HC541EE4	SN74HC241PWR	SN74HC377N	SN74HC574NE4
CD74HC541PWR	SN74HC241PWRE4	SN74HC377NE4	SN74HC574NSR
CD74HC573E	SN74HC251N	SN74HC377NSR	SN74HC574PWR
CD74HC573EE4	SN74HC259N	SN74HC540N	SN74HC574PWRE4
CD74HC574E	SN74HC259NE4	SN74HC540NE4	SN74HC574PWRG4
SN74HC138N	SN74HC273DBR	SN74HC540NSR	SN74HC595N
SN74HC138NE4	SN74HC273N	SN74HC540PWR	SN74HC595NE4
SN74HC139N	SN74HC273NE4	SN74HC540PWRE4	SN74HCT573PWR
SN74HC139NE4			



Approve Date 14-Sep-2021

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	Qual Device: <u>SN74HC273NSR</u>	Qual Device: <u>SN74HC374NSR</u>	QBS Product Reference: <u>CD74HC377PWR</u>	QBS Product Reference: <u>SN74HC240PWR</u>	QBS Product Reference: <u>SN74HC241PWR</u>	QBS Product Reference: <u>SN74HC273PWR</u>	QBS Product Reference: <u>SN74HC373PWR</u>
CDM	ESD - CDM	1500 V	1/3/0	-	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0
HBM	ESD - HBM	5000V	-	-	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0

Qualification Results Data Displayed as: Number of lots / Total sample size / Total failed

1	Data Displayed as. Number of fotar sample size / fotar falled										
Туре	Test Name / Condition	Duration	QBS Product Reference: <u>SN74HC374PWR</u>	QBS Product Reference: <u>SN74HC540PWR</u>	QBS Product Reference: <u>SN74HC541PWR</u>	QBS Product Reference: <u>SN74HC573APWR</u>	QBS Product Reference: <u>SN74HC574PWR</u>	QBS Product Reference: <u>SN74HCT573PWR</u>	QBS Process Reference: <u>SN74HC S245QPWRQ1</u>		
AC	Autoclave 121C	96 Hours	-	-	-	-	-	-	1/77/0		
CDM	ESD - CDM	1500 V	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0		
EC	Electrical Characterization	Per Datasheet Parameters	-	-	-	-	-	-	3/90/0		
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	-	-	-	-	1/77/0		
HBM	ESD - HBM	5000V	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0		
HTOL	Life Test, 150C	300 Hours	-	-	-	-	-	-	1/77/0		
HTSL	High Temp Storage Bake 150C	1000 Hours	-	-	-	-	-	-	1/45/0		
LU	Latch-up	(Per JESD78)	1/6/0	1/6/0	1/6/0	1/3/0	1/6/0	1/6/0	1/3/0		
тс	Temperature Cycle, -65/150C	500 Cycles	-	-	-	-	-	-	1/77/0		
WBP	Wire Bond Pull	Wires	-	-	-	-	-	-	1/30/0		

Qualification Results Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	QBS Process Reference: <u>SN74HC S273QPWRQ1</u>	QBS Package Reference: <u>1P8T245NSR</u>	QBS Package Reference: <u>SN74HC253NSR</u>	QBS Package Reference: <u>SN74HC257NSR</u>	QBS Package Reference: <u>ULQ2003AQDRQ1_RLF</u>	QBS Package Reference: <u>ULQ2003AQDRQ1_STDLF</u>
AC	Autoclave 121C	96 Hours	1/77/0	3/231/0	-	-	3/231/0	3/231/0
CDM	ESD - CDM	1500 V	1/3/0	-	1/3/0	-	-	-
EC	Electrical Characterization	Per Datasheet Parameters	No Fails	-	-	-	No Fails	-
HAST	Biased HAST, 130C/85%RH	96 Hours	1/77/0	-	-	-	-	3/231/0
HTOL	Life Test, 150C	300 Hours	1/77/0	-	-	-	-	-
HTOL	Life Test, 150C	408 Hours	-	-	-	-	-	3/231/0
HTSL	High Temp Storage Bake 150C	1000 Hours	1/45/0	-	-	-	1/45/0	1/45/0
HTSL	High Temp Storage Bake 170C	420 Hours	-	3/231/0	-	-	-	-
LU	Latch-up	(Per JEDC78)	1/6/0	-	-	-	-	-
тс	Temperature Cycle, -65/150C	500 Cycles	1/77/0	3/231/0	-	-	3/231/0	3/231/0
WBP	Wire Bond Pull	Wires	1/30/0	-	-	-	-	-
WBS	Wire Bond Shear	Wires	1/30/0	-	-	-	-	-

QBS: Qual By Similarity
Qual Device SN74HC374NSR is qualified at LEVEL1-260C
Qual Device SN74HC273NSR is qualified at LEVEL1-260C
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent TFSL options based on an activation energy of 0.7eV: 125C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
Green/Pb-free Status:
Qualified Pb-Free(SMT) and Green



Approve Date 14-Sep-2021

Qualification Results Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	Qual Device: <u>SN74HC273DBR</u>	QBS Product Reference: <u>SN74HC273PWR</u>	QBS Product Reference: <u>SN74HC541PWR</u>	QBS Product Reference: <u>SN74HC574PWR</u>	QBS Process Reference: <u>SN74HCS273QPWRQ1</u>	QBS Package Reference: <u>1M16374QDLREP</u>	QBS Package Reference: <u>1R16214CDL</u>
AC	Autoclave 121C	96 Hours	-	-	-	-	1/77/0	3/231/0	3/231/0
CDM	ESD - CDM	1500 V	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	-	-
ED	Electrical Characterization	Per Datasheet Parameters	-	-	-	-	Pass	Pass	Pass
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	-	-	1/77/0	-	-
HBM	ESD - HBM	5000V	-	1/3/0	1/3/0	1/3/0	-	-	-
HTOL	Life Test, 150C	300 Hours	-	-	-	-	1/77/0	-	-
HTSL	High Temp Storage Bake 150C	1000 Hours	-	-	-	-	1/45/0	-	-
HTSL	High Temp Storage Bake 170C	420 Hours	-	-	-	-	-	3/231/0	-
LU	Latch-up	(JESD78)	-	1/6/0	1/6/0	1/6/0	1/6/0	-	-
PC	Automotive Preconditioning Level 1	(Level 1- 260C)	-	-	-	-	No Fails	-	-
тс	Temperature Cycle, -65/150C	500 Cycles	-	-	-	-	1/77/0	3/231/0	4/308/0
WBP	Bond Pull	Wires	1/76/0	-	-	-	-	-	-
WBS	Ball Bond Shear	Wires	1/76/0	-	-	-	-	-	-

Qualification Results Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	QBS Package Reference: <u>BQ77PL900DL</u>	QBS Package Reference: <u>SN75976A1DL</u>	QBS Package Reference: <u>TLC5920DLR</u>
AC	Autoclave 121C	96 Hours	-	3/231/0	-
ED	Electrical Characterization	Per Data	-	1/Pass	-
HTSL	High Temp Storage Bake 170C	420 Hours	-	3/231/0	-
TC	Temperature Cycle, -65/150C	500 Cycles	3/231/0	3/231/0	4/308/0

- QBS: Qual By Similarity

- Qual Device SN74HC273DBR is qualified at LEVEL1-260C

Qual Device SN74HC273DBR is qualified at LEVEL1-260C
 Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
 The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
 The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
 The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles
 Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
 Green/Pb-free (SMT) and Green



Approve Date 14-Sep-2021

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	Qual Device: CD74HC377PWR	Qual Device: <u>SN74HC240PWR</u>	Qual Device: <u>SN74HC241PWR</u>	Qual Device: <u>SN74HC273PWR</u>	Qual Device: <u>SN74HC373PWR</u>	Qual Device: <u>SN74HC374PWR</u>	Qual Device: <u>SN74HC540PWR</u>
CDM	ESD - CDM	1500 V	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0
HBM	ESD - HBM	5000V	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0
LU	Latch-up	(per JESD78)	1/6/0	1/6/0	1/6/0	1/6/0	1/6/0	1/6/0	1/6/0

Qualification Results Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	Qual Device: <u>SN74HC541PWR</u>	Qual Device: <u>SN74HC573APWR</u>	Qual Device: <u>SN74HC574PWR</u>	Qual Device: <u>SN74HCT573PWR</u>	QBS Process Reference: <u>SN74HC S273QPWRQ1</u>	QBS Package Reference: <u>SN74HCS244QPWRQ1</u>
AC	Autoclave 121C	96 Hours	-	-	-	-	1/77/0	1/77/0
CDM	ESD - CDM	1500 V	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0
EC	Electrical Characterization	Cpk>1.67 Room, hot, and cold test	-	-	-	-	3/90/0	3/90/0
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	-	-	1/77/0	1/77/0
HBM	ESD - HBM	5000V	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0
HTOL	Life Test, 150C	300 Hours	-	-	-	-	1/77/0	1/77/0
HTSL	High Temp Storage Bake 150C	1000 Hours	-	-	-	-	1/45/0	1/45/0
LU	Latch-up	(per JESD78)	1/6/0	1/6/0	1/6/0	1/6/0	1/6/0	1/6/0
PC	Automotive Preconditioning Level 1	(Level 1-260C)	-	-	-	-	No Fails	No Fails
тс	Temperature Cycle, - 65/150C	500 Cycles	-	-	-	-	1/77/0	1/77/0

Туре	Test Name / Condition	Duration	Qual Device: <u>SN74HC541PWR</u>	Qual Device: <u>SN74HC573APWR</u>	Qual Device: <u>SN74HC574PWR</u>	Qual Device: <u>SN74HCT573PWR</u>	QBS Process Reference: <u>SN74HC S273QPWRQ1</u>	QBS Package Reference: <u>SN74HC S244QPWRQ1</u>
WBP	Wire Bond Pull	Wires	-	-	-	-	1/30/0	1/30/0
WBS	Wire Bond Shear	Wires	-	-	-	-	1/30/0	1/30/0

QBS: Qual <u>By</u> Similarity
 Qual Device SN74HC241PWR is qualified at LEVEL1-260C
 Qual Device SN74HC574PWR is qualified at LEVEL1-260C
 Qual Device CD74HC377PWR is qualified at LEVEL1-260C
 Qual Device SN74HC373PWR is qualified at LEVEL1-260C

Qual Device SN74HC210PWR is qualified at LEVEL1-260C
 Qual Device SN74HC240PWR is qualified at LEVEL1-260C
 Qual Device SN74HC573PWR is qualified at LEVEL1-260CG
 Qual Device SN74HC273PWR is qualified at LEVEL1-260CG
 Qual Device SN74HC273PWR is qualified at LEVEL1-260CG

Qual Device SN74HC374PWR is qualified at LEVEL1260C
 Qual Device SN74HC374PWR is qualified at LEVEL1260C
 Qual Device SN74HC541PWR is qualified at LEVEL1260C

- Qual Device SN74HC573APWR is qualified at LEVEL1-260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours - The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status: Qualified Pb-Free(SMT) and Green



Approve Date 14-Sep-2021

Qualification Results Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	Qual Device: <u>SN74HC273N</u>	QBS Product Reference: <u>CD74HC377PWR</u>	QBS Product Reference: <u>SN74HC240PWR</u>	QBS Product Reference: <u>SN74HC241PWR</u>	QBS Product Reference: <u>SN74HC273PWR</u>	QBS Product Reference: <u>SN74HC373PWR</u>	QBS Product Reference: <u>SN74HC374PWR</u>
CDM	ESD - CDM	1500 V	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0
HBM	ESD - HBM	5000V	-	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0
LU	Latch-up	(Per JED78)	-	1/6/0	1/6/0	1/6/0	1/6/0	1/6/0	1/6/0
тс	Temperature Cycle, -65/150C	500 Cycles	1/77/0	-	-	-	-	-	-

Qualification Results Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	QBS Product Reference: <u>SN74HC540PWR</u>	QBS Product Reference: <u>SN74HC541PWR</u>	QBS Product Reference: <u>SN74HC573APWR</u>	QBS Product Reference: <u>SN74HC574PWR</u>	QBS Product Reference: <u>SN74HCT573PWR</u>	QBS Process Reference: <u>SN74HC S273QPWRQ1</u>	QBS Package Reference: <u>SN74HCT540N</u>
AC	Autoclave 121C	96 Hours	-	-	-	-	-	1/77/0	3/231/0
CDM	ESD - CDM	1500 V	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	-
EC	Electrical Characterization	Per Datasheet Parameters	-	-	-	-	-	Pass	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	-	-	-	1/77/0	-
HBM	ESD - HBM	5000V	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	-
HTOL	Life Test, 150C	300 Hours	-	-	-	-	-	1/77/0	-
HTSL	High Temp Storage Bake 150C	1000 Hours	-	-	-	-	-	1/45/0	-

Туре	Test Name / Condition	Duration	QBS Product Reference: <u>SN74HC540PWR</u>	QBS Product Reference: <u>SN74HC541PWR</u>	QBS Product Reference: <u>SN74HC573APWR</u>	QBS Product Reference: <u>SN74HC574PWR</u>	QBS Product Reference: <u>SN74HCT573PWR</u>	QBS Process Reference: <u>SN74HC S273QPWRQ1</u>	QBS Package Reference: <u>SN74HCT540N</u>
HTSL	High Temp Storage Bake 170C	420 Hours	-	-	-	-	-	-	3/231/0
LU	Latch-up	(Per JESD78)	1/6/0	1/6/0	1/6/0	1/6/0	1/6/0	1/6/0	-
PC	Preconditioning Level 1	(Level 1- 260C)	-	-	-	-	-	No Fails	No Fails
TC	Temperature Cycle, -65/150C	500 Cycles	-	-	-	-	-	1/77/0	3/231/0

Qualification Results Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	QBS Package Reference: <u>TPA3122D2N</u>	QBS Package Reference: <u>UC3875N</u>
AC	Autoclave 121C	96 Hours	3/231/0	3/231/0
HTSL	High Temp Storage Bake 170C	420 Hours	3/231/0	3/231/0
TC	Temperature Cycle, -65/150C	500 Cycles	3/231/0	3/231/0

- QBS: Qual By Similarity - Qual Device SN74HC273N is qualified at LEVEL1-260C

Qual Device SN74HC273N is qualified at LEVEL1-260C
 Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
 The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
 The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
 The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
 The following are equivalent TESL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
 The following are equivalent TTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
 The following are equivalent TTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
 The following are equivalent TTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
 The following are equivalent TTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
 The following are equivalent TTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
 The following are equivalent TTSL options based on an activation energy of 0.7eV: 150C/1b Cycles and -65C/150C/500 Cycles
 Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
 Green/Pb-free Status:
 Qualitied Pb-Free(SMT) and Green



Qualification Report Gatorade Expansion 16 pin PDIP SN74HC138, CD74HC138 SN74HC595, SN74HC139, SN74HC151, SN74HC157 SN74HC165, SN74HC166, SN74HC174, CD74HC237 CD74HC238, SN74HC251, CD74HC259, SN74HC259, SN74HC367

Approve Date 09-Jul-2021

Qualification Results Data Displayed as: Number of lots / Total sample size / Total failed

Тур е	Test Name / Condition	Duration	Qual Device: <u>SN74HC595</u> <u>N</u>	QBS Product Reference: <u>SN74HCS137QPWRQ</u> <u>1</u>	QBS Product Reference: <u>SN74HCS138QPWRQ</u> <u>1</u>	QBS Product Reference: <u>SN74HCS139QPWRQ</u> <u>1</u>	QBS Product Reference: <u>SN74HCS151QPWRQ</u> <u>1</u>	QBS Product Reference: <u>SN74HCS157QPWRQ</u> <u>1</u>	QBS Product Reference: <u>SN74HC S165QDRQ</u> <u>1</u>
ED	Electrical Distribution s	Cpk>1.6 7 Room, hot, and cold test	-	1/30/0	1/30/0	1/30/0	1/30/0	1/30/0	1/30/0
CDM	ESD - CDM	1500V	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0
HBM	ESD - HBM	7000V	-	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0
LU	Latch-up	(Per AEC- Q100- 004)	-	1/6/0	1/6/0	1/6/0	1/6/0	1/6/0	1/6/0

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Typ e	Test Name / Condition	Duratio n	QBS Product Reference: <u>SN74HCS166QDR</u> <u>Q1</u>	QBS Product Reference: <u>SN74HC S174QPWR</u> <u>Q1</u>	QBS Product Reference: <u>SN74HC S237QPWR</u> <u>Q1</u>	QBS Product Reference: <u>SN74HC S238QPWR</u> <u>Q1</u>	QBS Product Reference: <u>SN74HC S251QPWR</u> <u>Q1</u>	QBS Product Reference: <u>SN74HC S259QPWR</u> <u>Q1</u>	QBS Product Reference: <u>SN74HC S367QPWR</u> <u>Q1</u>
ED	Electrical Distribution s	Cpk>1.6 7 Room, hot, and cold test	1/30/0	1/30/0	1/30/0	1/30/0	1/30/0	1/30/0	1/30/0
CD M	ESD - CDM	1500V	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0
HB M	ESD - HBM	7000V	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0	1/3/0
LU	Latch-up	(Per AEC- Q100- 004)	1/6/0	1/6/0	1/6/0	1/6/0	1/6/0	1/6/0	1/6/0

Qualification Results Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	QBS Product Reference: <u>SN74HC S595QPWRQ1</u>	QBS Process Reference: <u>SN74HC S74QPWRQ1</u>	QBS Package Reference: <u>SN74HC595N</u>	QBS Package Reference: <u>TLV9054IDR</u>
ED	Electrical Characterization	Per Datasheet Parameters	-	-	Pass	1/30/0
ED	Electrical Distributions	Cpk>1.67 Room, hot, and cold test	3/90/0	3/90/0	-	-
CDM	ESD - CDM	1500V	-	1/3/0	-	1/3/0
CDM	ESD - CDM	2000V	1/3/0	-	-	-
HBM	ESD - HBM	4000V	-	-	-	1/3/0
HBM	ESD - HBM	9000V	1/3/0	-	-	-
HBM	ESD - HBM	7000V	-	1/3/0	-	-
LU	Latch-up	(Per AEC-Q100-004)	1/6/0	1/6/0	-	1/6/0
ELFR	Early Life Failure Rate, 125C	48 Hours	-	3/2400/0	-	-
HTOL	Life Test, 150C	300 Hours	1/77/0	3/231/0	-	1/77/0
UHAST	Unbiased HAST 130C/85%RH	96 Hours	-	-	-	3/231/0
AC	Autoclave 121C	96 Hours	1/77/0	3/231/0	3/225/0	-
HAST	Biased HAST, 130C/85%RH	96 Hours	1/77/0	3/231/0	-	3/231/0
HTSL	High Temp Storage Bake 150C	1000 Hours	1/45/0	3/135/0	-	-

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Туре	Test Name / Condition	Duration	QBS Product Reference: <u>SN74HC S595QPWRQ1</u>	QBS Process Reference: <u>SN74HCS74QPWRQ1</u>	QBS Package Reference: <u>SN74HC595N</u>	QBS Package Reference: <u>TLV9054IDR</u>
HTSL	High Temp Storage Bake 170C	420 Hours	-	-	3/231/0	3/231/0
TC	Temperature Cycle, - 65/150C	500 Cycles	1/77/0	3/231/0	3/231/0	3/231/0

- OBS: Qual By Similarity

- Qual Device SN74HC595N is qualified at Not Classified

- The following was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
 - The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
 The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/ Green/Pb_free Status:

Qualified Pb-Free(SMT) and Green



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Qualification Report

Gatorade Expansion 16 Pin PDIP SN74HC138N, CD74HC138N, SN74HC595N, SN74HC139N, SN74HC151N, SN74HC157N, SN74HC165N, SN74HC166N, SN74HC174N, CD74HC237N, CD74HC238N, SN74HC251N, CD74HC259N, SN74HC259N, SN74HC367N

Approve Date 21-Jul-2021

Qualification Results Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	Qual Device: <u>SN74HC138N</u>	QBS Product Reference: <u>SN74HCS16507QDRQ1</u>	QBS Product/Process Reference: <u>SN74HC S74QPWRQ1</u>	QBS Process Reference: <u>SN74HC S595QPWRQ1</u>	QBS Package Reference: L293DNE	QBS Package Reference: <u>SN74HC00N</u>
EC	Electrical Characterization	Cpk>1.67	-	1/30/0	3/90/0	-	-	-
CDM	ESD - CDM	1500 V	-	1/3/0	1/3/0	-	-	-
HBM	ESD - HBM	7000 V	-	1/3/0	1/3/0	-	-	-
LU	Latch-up	(Per AEC-Q100-004)	-	1/6/0	1/6/0	-	-	-
ELFR	Early Life Failure Rate, 125C	48 Hours	-	-	3/2400/0	-	-	-
HTOL	Life Test, 150C	300 Hours	-	-	3/231/0	1/77/0	-	-
AC	Autoclave 121C	96 Hours	-	-	3/231/0	1/77/0	3/231/0	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	3/231/0	1/77/0	-	1/77/0
HTSL	High Temp Storage Bake 150C	1000 Hours	-	-	3/135/0	1/45/0	-	-
HTSL	High Temp Storage Bake 170C	420 Hours	-	-	-	-	3/231/0	-
TC	Temperature Cycle, -65/150C	500 Cycles	-	-	3/231/0	1/77/0	3/225/0	1/77/0
WBP	Wire Bond Pull	Wires	1/76/0	-	-	-	-	-
WBS	Wire Bond Shear	Wires	1/76/0	-	3/231/0	-	-	-

- QBS: Qual By Similarity

- Qual Device SN74HC138N is qualified at LEVEL1-260CG

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours - The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

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Green/Pb-free Status: Qualified Pb-Free(SMT) and Green

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